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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Etsuo Koyama
 Hiroyoshi Matsumura

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Teedia Co., Ltd.

Internal Address: _____

Street Address: 3-1-1 Higashi-Ikebukuro

Toshima-ku

City: Tokyo

State: _____

Country: Japan

Zip: 170-6020

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) October 31, 2006

- Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other _____

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

11/541,783

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Matthew A. Pequinot

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6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40

- Authorized to be charged by credit card
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 None required (government interest not affecting title)

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Authorized User Name Matthew A. Pequinot

9. Signature:

Matthew A. Pequinot

Signature

November 22, 2006

Date

Matthew A. Pequinot
 Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

2

ASSIGNMENT

WHEREAS, we, **Etsuo Koyama**, a citizen of **Japan**, mailing address c/o **Tecdia Co., Ltd.**, 3-1-1 Higashi-Ikebukuro, Toshima-ku, **Tokyo**, 170-6020 **Japan**, and **Hiroyoshi Matsumura**, a citizen of **Japan**, residing mailing address c/o **Tecdia Co., Ltd.**, 3-1-1 Higashi-Ikebukuro, Toshima-ku, **Tokyo**, 170-6020 **Japan**, are the inventors of an invention in **OPTICAL SWITCH AND OPTICAL ADD/DROP MULTIPLEXER**, the specification of which was filed in the United States Patent and Trademark Office on **October 2, 2006**; and

WHEREAS, **Tecdia Co., Ltd.**, incorporated in **Japan**, with a place of business at 3-1-1 Higashi-Ikebukuro, Toshima-ku, **Tokyo**, 170-6020 **Japan**, is desirous of obtaining the entire right, title and interest in, to and under the said invention and any patent application made therewith;


NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we the said **Etsuo Koyama** and **Hiroyoshi Matsumura** have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said **Tecdia Co., Ltd.**, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and any said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said invention in any country or countries foreign to the United States, and all Letters Patent which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof and all rights of priority in any such country or countries based upon the filing of the said application for Letters Patent of the United States which are created by any law, treaty or international convention; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said **Tecdia Co., Ltd.** its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said **Tecdia Co., Ltd.**, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said **Tecdia Co., Ltd.**, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.


IN TESTIMONY WHEREOF, we hereunto set our hands and seals the day and year set opposite our respective signatures.

Date October 31, 2006 _____ L.S.



Etsuo Koyama

Date October 31, 2006 _____ L.S.



Hiroyoshi Matsumura

Witnessed by: 

PATENT